

Form PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)	Docket Number (Optional) 4373.2US (00-0036.02/US)	Application Number Not Yet Assigned
	Applicant Chopra et al.	
	Filing Date July 14, 2003	Group Art Unit Unknown

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
L.J.M.-E	5,780,358	07/1998	Zhou et al.			
L.J.M.-E	5,836,806	11/1998	Cadien et al.			
L.J.M.-E	5,840,629	11/1998	Carpio			
L.J.M.-E	5,846,398	12/1998	Carpio			
L.J.M.-E	5,863,307	01/1999	Zhou et al.			
L.J.M.-E	5,897,375	04/1999	Watts et al.			
L.J.M.-E	5,954,975	09/1999	Cadien et al.			
L.J.M.-E	5,954,997	09/1999	Kaufman et al.			
L.J.M.-E	5,985,748	11/1999	Watts et al.			
L.J.M.-E	6,001,730	12/1999	Farkas et al.			
L.J.M.-E	6,046,099	04/2000	Cadien et al.			
L.J.M.-E	6,083,419	07/2000	Grumbine et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
L.J.M.-E	WO 98/49723	11/1998	PCT	—	—		
L.J.M.-E	WO 00/00561	01/2000	PCT	—	—		
L.J.M.-E	WO 00/28586	05/2000	PCT	—	—		
L.J.M.-E	WO 01/21724 A1	03/2001	PCT	—	—		

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

L.J.M.-E	Lee, Michael G., et al., "Planarization of Copper/Polyimide for Multilevel Interconnects by Chemical Mechanical Polishing (CMP)," VMIC (1996), pp. 395-397, Proceedings of 13th Internat'l. VLSI Multilevel Interconnection Conf., Santa Clara, CA, June 18-20, 1996.
L.J.M.-E	Stavreva, Z., et al., "Chemical--Mechanical Polishing of Copper for Interconnect Formation," Microelectronic Eng., Vol. 33 (1997), pp. 249-257.
L.J.M.-E	Seung-Mahn Lee, et al., "Study of Slurry Chemistry in Chemical Mechanical Polishing (CMP) of Copper," Database Chemabs Online!, Chemical Abstracts, Columbus, Ohio, Proceedings--Electrochemical Society (2000).

EXAMINER <i>Lynette J. Ume-Eurini</i>	DATE CONSIDERED 3/1/2005
--	------------------------------------

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

Form PTO-1449

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)
4373.2US (00-0036.02/US)Application Number
Not Yet Assigned

Applicant Chopra et al.

Filing Date July 14, 2003

Group Art Unit Unknown

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
L.T.M.E.	6,063,306	05/2000	Kaufman et al.			
L.T.M.E.	6,083,840	07/2000	Mravic et al.			
L.T.M.E.	6,100,197	08/2000	Hasegawa			
L.T.M.E.	2002/0022370 A1	02/2002	Sun et al.			
L.T.M.E.	2002/0033382 A1	03/2002	Kaufman et al.			
L.T.M.E.	6,375,693 B1	04/2002	Cote et al.			
L.T.M.E.	6,409,781 B1	06/2002	Wojtczak et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

L.T.M.E.		Seung-Mahn Lee, et al., "Fundamental Study of Iodate and Iodine Based Slurries for Copper CMP," Mat. Res. Soc. Symp., Vol. 613, ©2000 Materials Research Society, pp. E7.8.1-E7.8.6.
L.T.M.E.		PCT International Search Report of 7/30/02.

EXAMINER

Lynette T. Umeg-Eunini

DATE CONSIDERED

3/1/2005

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.



Approved for use through 10/31/2002. OMB 0651-0031

U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Complete if Known

Application Number	10/620,002
Filing Date	July 14, 2003
First Named Inventor	Chopra et. al.
Group Art Unit	3723
Examiner Name	unknown
Attorney Docket Number	2269-4373.2US (00-0036.02/US)

U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

3/1/2005

¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. **DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO:** Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.